Description

The CMN3008SF5 is the N-Channel enhancement mode power field effect transistors with high cell density, trench technology. This high density process and design have been optimized switching performance and especially tailored to minimize on-state resistance.

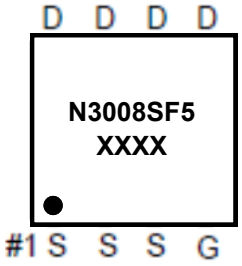
Applications

- Battery management
- Power management
- Load switch

Features

- V_{DS}: 30V
- I_D: 57A
- $R_{DS_{ON}}$ (@V_{GS}=10V) : < 7.5mΩ
- $R_{DS_{ON}}$ (@V_{GS}=4.5V) : < 11.5mΩ
- High density cell design for extremely low $R_{DS_{ON}}$
- Excellent on-resistance and DC current capability

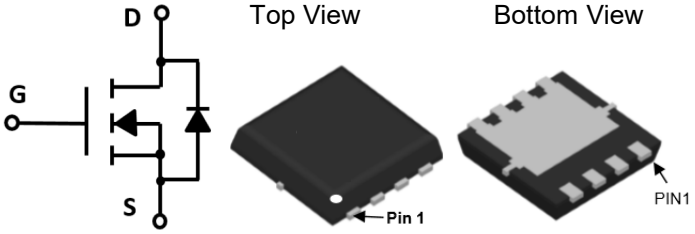
Marking Information



Marking Code = N3008SF5

Date Code = XXXX

Equivalent Circuit and Pin Configuration



Ordering Information

Part Number	Packaging	Reel Size
CMN3008SF5	5000/Tape & Reel	13 inch

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter		Symbol	Maximum	Unit
Drain-source Voltage		V_{DS}	30	V
Gate-source Voltage		V_{GS}	±20	V
Drain Current[1][6]	T_C=25°C	I_D	57	A
	T_C=100°C		36	A
	T_A=25°C	I_D	20	A
	T_A=100°C		13	A
Pulsed Drain Current[3]		I_{DM}	114	A
Total Power Dissipation[4]	T_C=25°C	P_D	42	W
	T_A=25°C		5.0	W
Thermal Resistance Junction-to-Ambient[2][5]		$R_{\theta JA}$	25	°C/W
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	3	°C/W
Junction and Storage Temperature Range		T_J,T_{STG}	-55 to +150	°C

Electrical Characteristics (T_J=25 ℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V,I_D=250μA	30			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V,V_{GS}=0V,T_C=25°C			1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	1.0		2.5	V
Static Drain-Source on-Resistance	$R_{DS(on)}$	V_{GS}=10V,I_D=20A		6.0	7.5	mΩ
		V_{GS}=4.5V,I_D=16A		9.0	11.5	
Diode Forward Voltage	V_{SD}	I_S=20A,V_{GS}=0V		0.8	1.2	V
Maximum Body-Diode Continuous Current	I_S				57	A
Dynamic Parameters						
Input Capacitance	Ciss	VDS=20V,VGS=0V,f=1MHz		1060		pF
Output Capacitance	Coss			121		
Reverse Transfer Capacitance	Crss			104		
Switching Parameters						
Total Gate Charge	Qg	V_{GS}=10V,V_{DS}=20V,I_D=20A		22.1		nC
Gate Source Charge	Qgs			3.3		
Gate Drain Charge	Qgd			5.7		
Turn-on Delay Time	$t_{D(on)}$	V_{GS}=10V,V_{DD}=20V, ID=20A,R_{GEN}=3Ω		12		ns
Turn-on Rise Time	tr			6.8		
Turn-off Delay Time	$t_{D(off)}$			39		
Turn-off Fall Time	tf			10		

Noted: (1) Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.

(2) The value of $R_{\theta JA}$ is measured with the device mounted on lin2 FR-4 board with 2oz.Copper,in a still air environment with T_A =25°C.The Power dissipation PDSM is based on $R_{\theta JA}$ t≤10s and the maximum allowed junction temperature of 150°C.The value in any given application depends on the user's specific board design.

(3) Single pulse width limited by junction temperature $T_{J(MAX)}$ = 150°C.

(4) The power dissipation PD is based on $T_{J(MAX)}$ = 150°C,using junction-to-case thermal resistance, and is more useful in setting the upper Dissipation limit for cases where additional heatsinking is used.

(5) The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JA}$ and case to ambient.

(6) The maximum current rating is package limited.

Typical Performance Characteristics

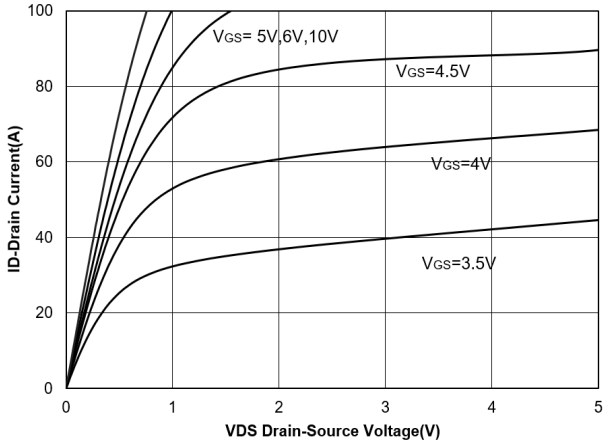


Figure 1. Output Characteristics

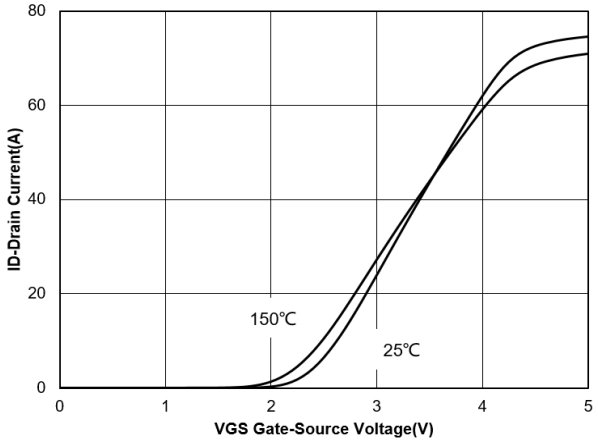


Figure 2. Transfer Characteristics

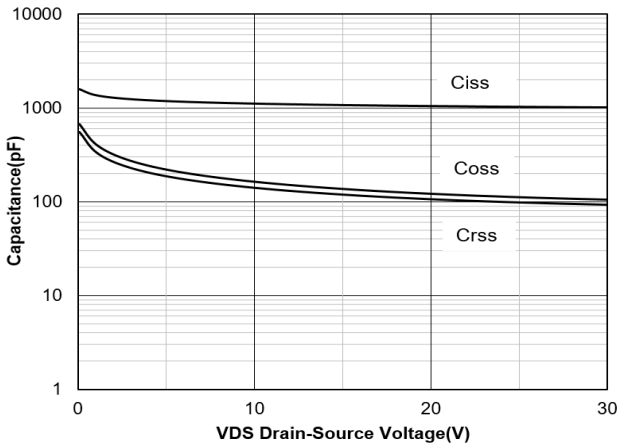


Figure 3. Capacitance Characteristics

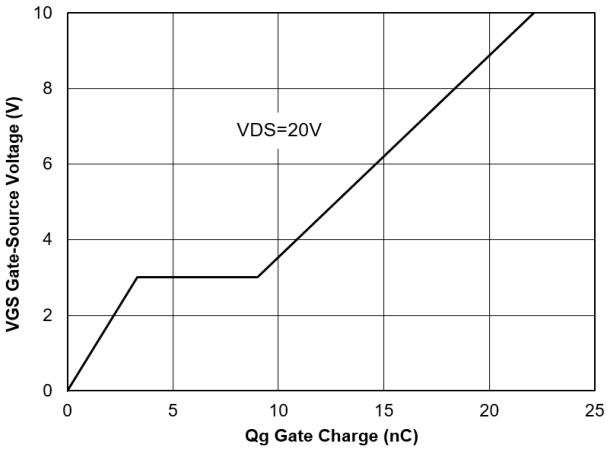


Figure 4. Gate Charge

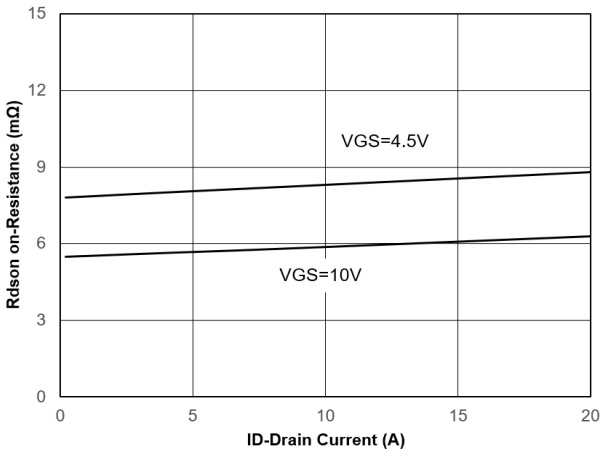


Figure 5. Drain-Source on Resistance

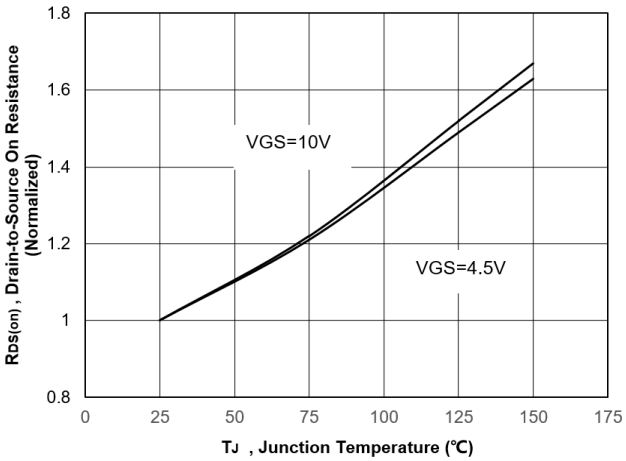


Figure 6. Normalized On-Resistance Vs. Temperature

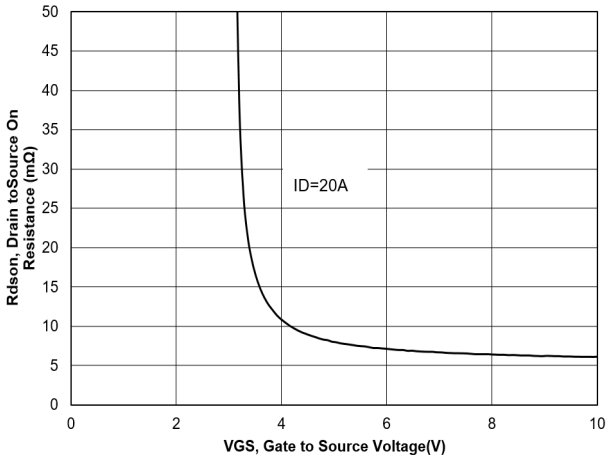


Figure 7. Typical Drain to Source ON Resistance VS Gate Voltage and Drain Current

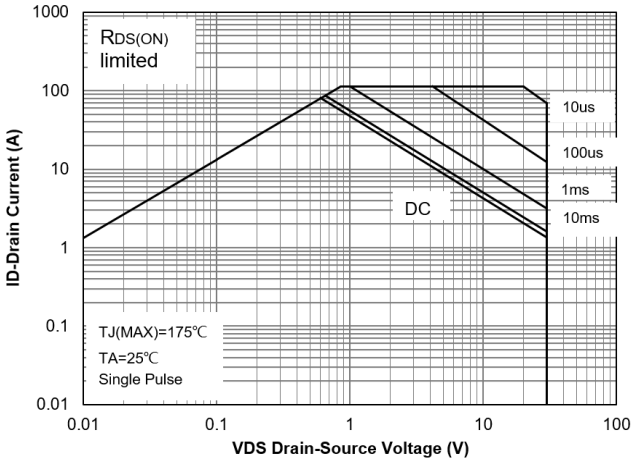


Figure 8. Safe Operation Area

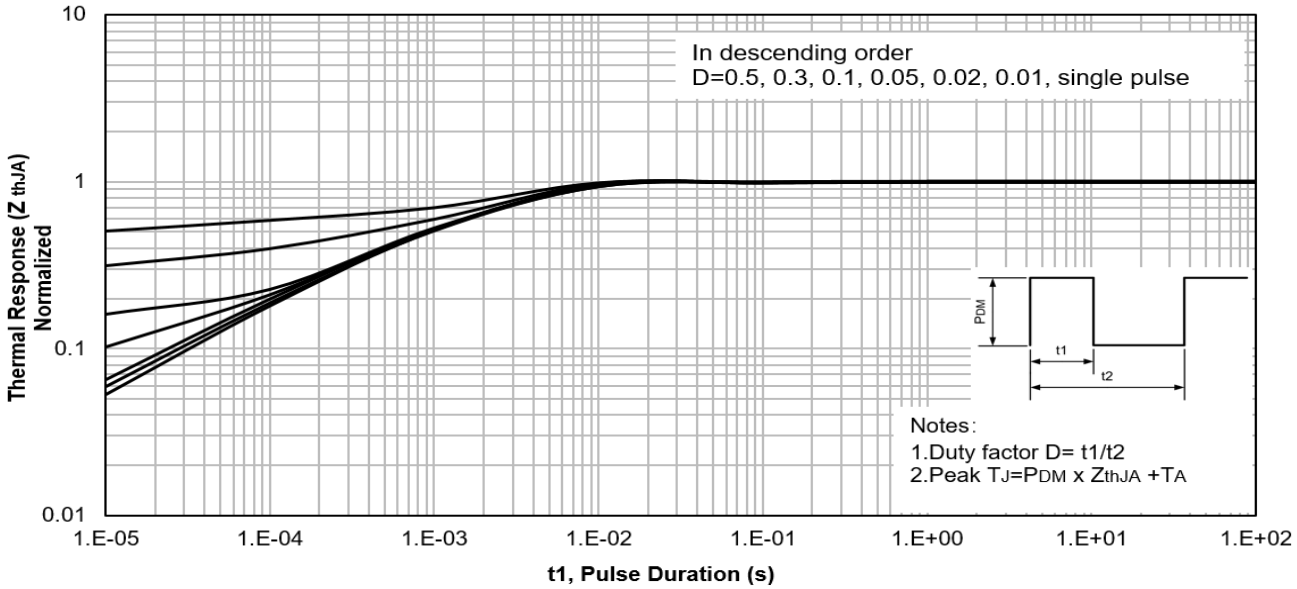


Figure 9. Maximum Effective Transient Thermal Impedance,Junction-to-Case

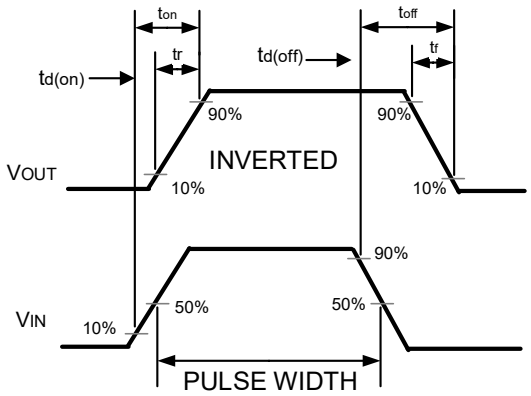
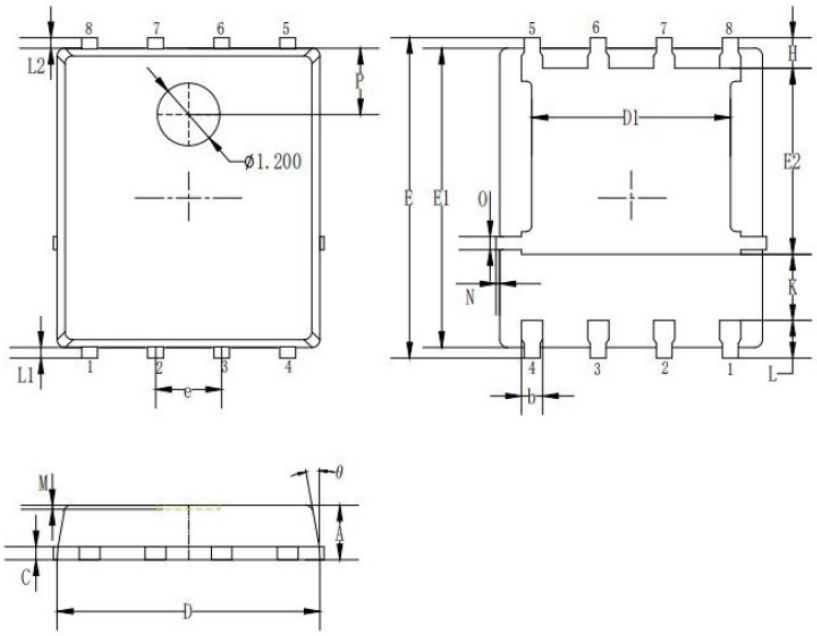


Figure 10. Switching wave

DFN 5x6 Package Outline Drawing



Symbol	Millimeters		
	Min.	Nom.	Max.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
c	0.20	0.25	0.35
D	4.90	5.05	5.20
D1	3.72	3.82	3.92
E	6.00	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF		
θ	8°	10°	12°
M	0.08 REF		
N	0	--	0.15
O	0.25 REF		
P	1.28 REF		

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